

CERAMIC DISC CAPACITORS CHARACTERISTICS



項目 ITEM	規格 SPECIFICATION		檢測方法及條件 TEST METHOD AND CONDITION															
7. 焊錫 附着 性及 焊錫 耐熱 性 Resistance to solder heat and Solder ability of leads	靜電容量 變化率 Capacitance Change	T.C.: ±5% or ±0.5PF	將元件端子線浸入240°C ±5°C的溶錫內，端子線浸至離本體邊緣2.0-3.0mm處，並保持3+1/-0秒。試驗前，將元件放置85+3/-0°C中預熱，5分鐘後再進行焊錫試驗；試驗後，元件須放置室溫中24小時後方可進行電氣特性的測試。 The lead wire shall be immersed into the melted solder of 240°C ±5°C up to about 2.0 to 3.0 mm from the main body for 3+1/-1 seconds. Capacitor shall be measured after leaving for 24 hours at room temperature.															
		HIK、S.C.: Y5E、Y5P、BN: ±10% X7R、Y5R: ±15% Y5T、Y5U、Z5U: ±20% Z5V、Y5V: ±30%																
	Q OR DF	T.C.: ①C<30PF: Q≥400+20xC ②C≥30PF: Q≥1000																
		HIK: ①Y5E, Y5P, X7R, Z5U, Y5U: DF≤2.5% ②Z5V, Y5V: DF≤5% ③BN, Y5T: DF≤0.5%, Y5R: DF≤0.2% S.C.: ①Y5P, Y5U: DF≤5% ②Y5V: Df≤7%																
絕緣電阻 Insulation Resistance	T.C.: 10000M Ω min HIK: 5000M Ω min S.C.: 100M Ω min																	
8. 溫度循環 Temp. Cycle	外觀 Appearance	無缺陷 No marked defect	將電容器進行如下五個溫度循環試驗： Capacitor shall be subjected to five cycles of the temperature cycle as following: <table border="1" data-bbox="1003 1048 1453 1227"> <thead> <tr> <th>Step</th> <th>Temp.(°C)</th> <th>Time</th> </tr> </thead> <tbody> <tr> <td>1</td> <td>Min rated temp(+0-3)</td> <td>30min</td> </tr> <tr> <td>2</td> <td>25</td> <td>30min</td> </tr> <tr> <td>3</td> <td>Max rated temp(+0-3)</td> <td>30min</td> </tr> <tr> <td>4</td> <td>25</td> <td>30min</td> </tr> </tbody> </table> 放置室溫下一段時間再測量其電氣特性： Measure at room temperature after cooling for: T.C.: 24Hr HIK、S.C.: 48Hr	Step	Temp.(°C)	Time	1	Min rated temp(+0-3)	30min	2	25	30min	3	Max rated temp(+0-3)	30min	4	25	30min
	Step	Temp.(°C)		Time														
	1	Min rated temp(+0-3)		30min														
	2	25		30min														
3	Max rated temp(+0-3)	30min																
4	25	30min																
靜電容量 Capacitance	T.C.: ±5% or ±0.5PF max. HIK、(S.C.): Y5E、Y5P、BN: ±10%; X7R、Y5R: ±15%; Y5T、Y5U、Z5U: ±20%; Z5V、Y5V: ±30%。																	
Q OR DF	T.C.: C<30PF: Q≥400+20xC C≥30PF: Q≥1000 HIK Y5E, Y5P, X7R, Y5U, Z5U DF≤5% Y5V, Z5V DF≤7.5% BN, Y5T DF≤1% Y5R DF≤0.5% S.C. Y5P, Y5U DF≤7.5% Y5V DF≤10%																	
絕緣電阻 Insulation Resistance	與初始規格值一致 To satisfy the specified initial value.																	
9. 耐濕負荷 Humidity loading	外觀 Appearance	無顯著之異常現象 No marked defect	在溫度40(±2°C)、相對濕度95%的狀態下，連續施加直流額定電壓（充電電流為50mA以下）500(+24-0)小時； 試驗後置于室溫中： T.C.類規格需放置24小時以上方可測定其電氣特性； HIK、半導體類規格需放置48小時以上方可測定其電氣特性。 Apply rated voltage for 500(+24-0)hours at 40(±2°C) in 95% RH Charge and discharge current 50mA max. Leave the capacitors in ambient condition for over the following time. Measurement T.C.: 24Hrs HIK、S.C.: 48Hrs															
	靜電容量 變化率 Capacitance Change	T.C.: ±7.5% or ±0.75PF max. HIK、半導體類 (S.C.): Y5E、Y5P、BN: ±15% X7R、Y5R: ±20% Y5T、Y5U、Z5U: ±25% Z5V、Y5V: ±35%																
	Q OR DF	T.C.: ①C<10PF: Q≥200+10×C ②10PF≤C<30PF: Q≥275+2.5×C ③C≥30PF: Q≥350																
		HIK: Y5E, Y5P, X7R, Y5U, Z5U DF≤5% Y5V, Z5V DF≤7.5% BN, Y5T DF≤1% Y5R DF≤0.5% 半導體類 (S.C.): Y5P, Y5U DF≤7.5% Y5V Df≤10%																
絕緣電阻 Insulation resistance	500M Ω min.or 25M Ω XUF min.																	